



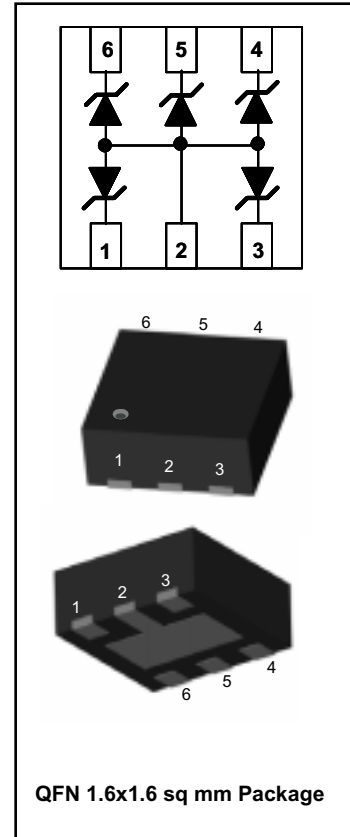
DATA SHEET

PJQMF05LC

5-TVS/ZENER ARRAY FOR ESD AND LATCH-UP PROTECTION

VOLTAGE 5 Volts **POWER** 100 Watts

This 5-TVS/Zener Array has been designed to Protect Sensitive Equipment against ESD and to prevent Latch-Up events in CMOS circuitry operating at 5Vdc and below. This TVS array offers an integrated solution to protect up to 5 data lines where the board space is a premium.
Pb free product are available : 99% Sn above can meet RoHS environment substance directive request



FEATURES

- 100W Power Dissipation (8X20usec Waveform)
- Low Leakage Current, Maximum of 2uA @5Vdc
- Very Low Clamping Voltage, Max of 10V @ 9Apk 8X20 usec
- IEC61000-4-2 ESD 20KV air, 15KV Contact Compliance
- Max off state Capacitance of 90pF @ 0Vdc 1 MHz
- New SMT package QFN 1.6mmx1.6mm; Max Height of 0.75mm
- Same Footprint compared to the SOT-563

APPLICATIONS

Case: QFN 1.6x1.6 plastic case.
Terminals : Solderable per MIL-STD-750, Method 2026
SIM Card Port Protection (Mobile Phone)
Portable Instrumentation
Mobile Phones and Accessories
Memory Card Port Protection
Marking Code: FA

MAXIMUM RATINGS (Per Device)

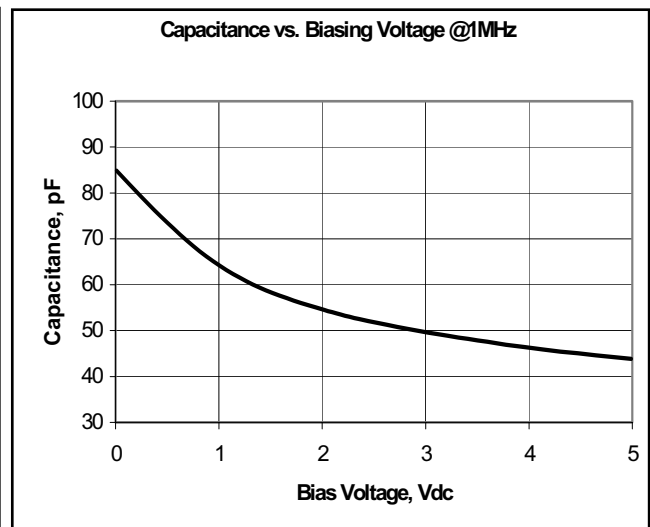
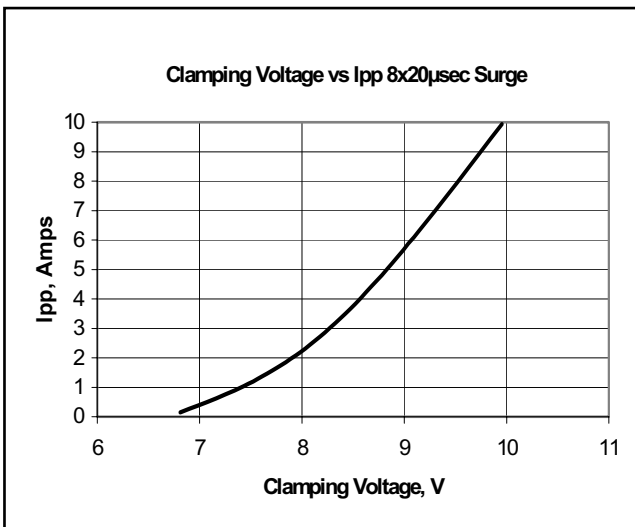
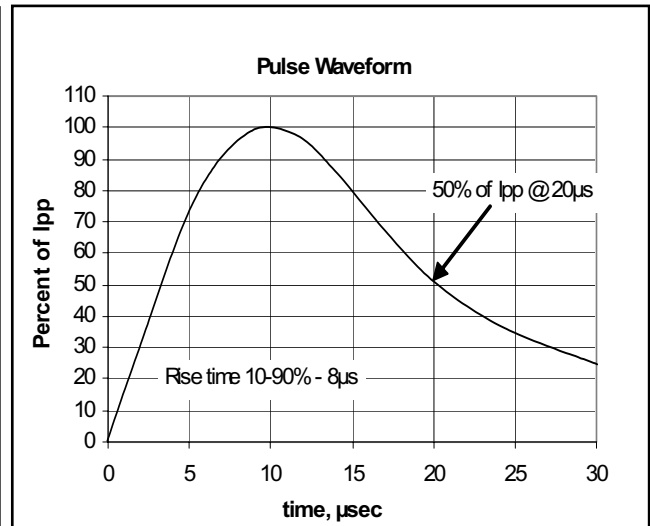
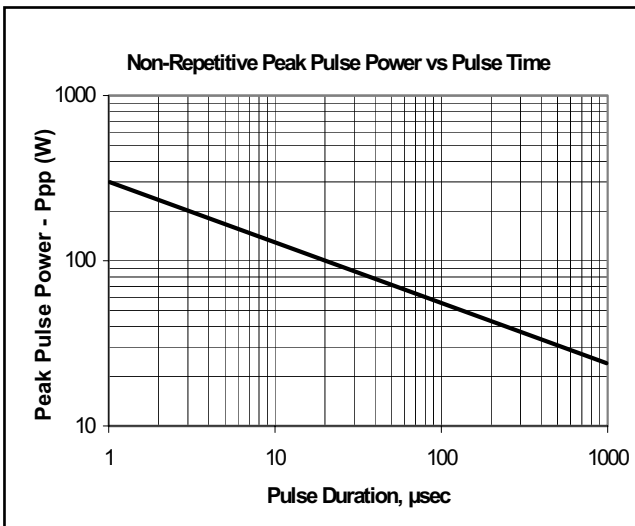
Parameter	Symbol	Value	Units
Peak Pulse Power 8 × 20 usec Waveform	P _{PP}	100	W
Peak Pulse Current 8 × 20 usec Waveform	I _{PP}	10	A
ESD Voltage (HBM)	V _{ESD}	>25	kV
Operating Temperature	T _L	-55 to +125	°C
Storage Temperature	T _{STG}	-55 to +150	°C



ELECTRICAL CHARACTERISTICS(Per Device) Tj=25°C

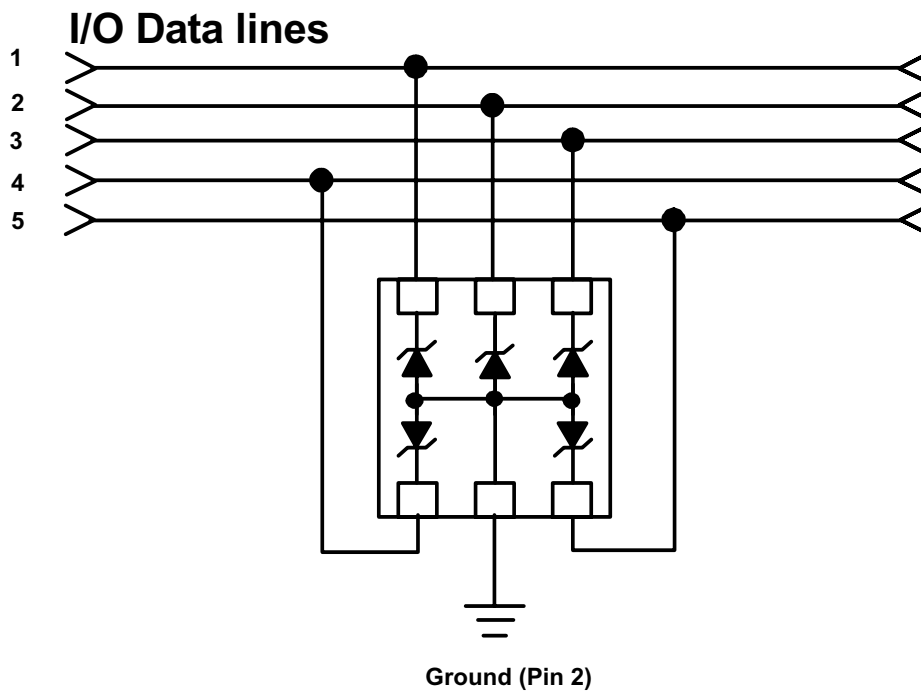
Parmeter	Symbol	Conditions	Min	Typical	Max.	Units
Reverse Stand-Off Voltage	V_{WRM}				5	V
Reverse Breakdown Voltage	V_{BR}	$I_{BR} = 1\text{mA}$	6		7.2	V
Reverse Leakage Current	I_R	$V_R = 5\text{V}$			2.0	μA
Clamping Voltage (8x20 usec)	V_{CL}	$I_{PP} = 5\text{A}$			9	V
Clamping Voltage (8x20 usec)	V_{CL}	$I_{PP} = 9\text{A}$			10	V
Off State Junction Capacitance	C_J	0Vdc Bias F=1MHz Between 1/O pins and pin 2			90	pF
Off State Junction Capacitance	C_J	5Vdc Bias F=1MHz Between 1/O pins and pin 2			45	pF

TYPICAL CHARACTERISTICS





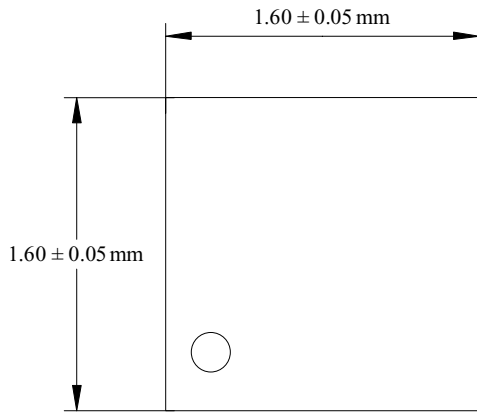
TYPICAL APPLICATION EXAMPLE



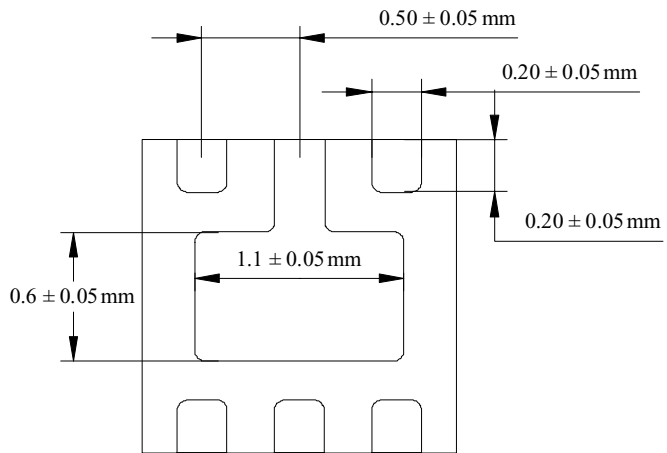


PACKAGE DIMENSIONS AND SUGGESTED BOND PAD LAYOUT

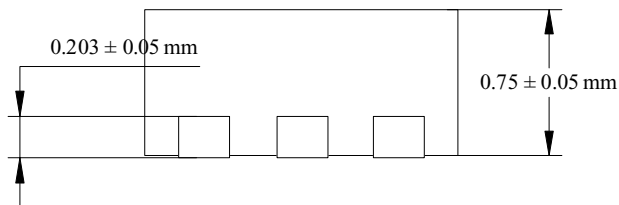
TOP VIEW



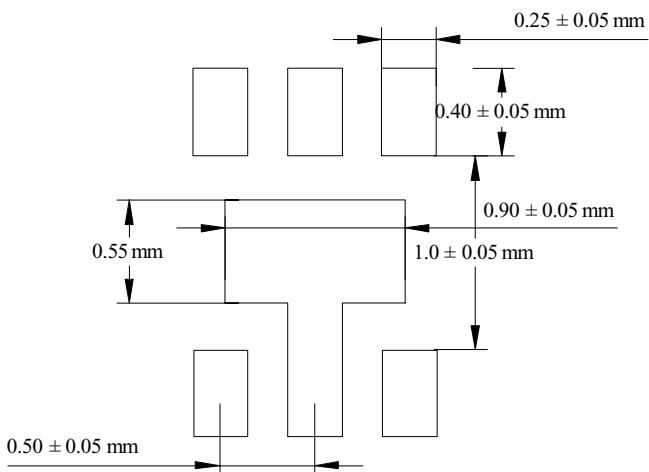
BOTTOM VIEW



SIDE VIEW



PREFERRED



ALTERNATE

